

AMENDMENTS TO THE CLAIMS:

1. (Currently amended) An image pickup device including comprising:

a light-transmissible board having a wiring pattern formed on one surface thereof and containing an optical filter disposed thereon; and

an image pickup element having a photodetecting portion formed on the same surface thereof, said image pickup element being mounted in flip-chip style on the one surface of said light-transmissible board so that the photodetecting portion of the image pickup element is opposed to an area where the wiring pattern is not formed;

wherein said wiring pattern is configured to match an electrode arrangement of said image pickup element and a terminal arrangement of a connector.
2. (Original) The image pickup device as claimed in claim 1, wherein said optical filter is an infrared rays cutting filter.
3. (Previously amended) The image pickup device as claimed in claim 1, wherein a peripheral edge portion of said image pickup element is sealed with resin.
4. (Currently amended) A camera module including comprising:

an optical filter;

an image pickup element having a photodetecting portion formed on the same surface thereof;
and

a lens holder unit comprising a lens, said lens being mounted on above the other surface of said light-transmissible board so as to be located above said photodetecting portion of said image pickup element, said image pickup element being mounted in a flip-chip style on the one surface of said light-transmissible board so that the photodetecting portion of the image pickup element is opposed to an area where the wiring pattern is not formed;

wherein said wiring pattern is configured to match an electrode arrangement of said image pickup element and a terminal arrangement of a connector.

5. (Currently amended) A camera system using a camera module including comprising:

a light-transmissible board having a wiring pattern formed on one surface thereof and containing an optical filter disposed thereon;

an image pickup element having a photodetecting portion formed on the same surface thereof;
and

a lens holder unit comprising a lens, said lens being mounted on above the other surface of said light-transmissible board so as to be located above said photodetecting portion of said image pickup element, said image pickup element being mounted in flip-chip style on the one surface of said light-transmissible board so that the photodetecting portion of the image pickup element is opposed to an area where the wiring pattern is not formed;

wherein said wiring pattern is configured to match an electrode arrangement of said image pickup element and a terminal arrangement of a connector.